

TYPES T1486, T1487

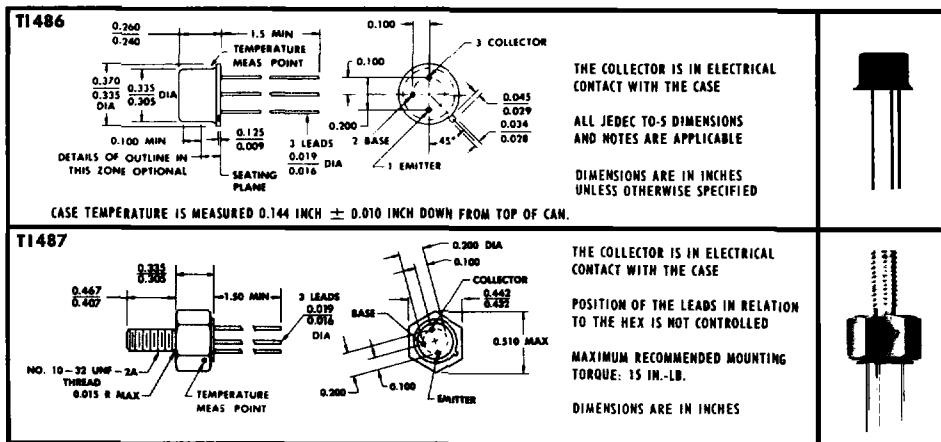
N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPES T1486, T1487
BULLETIN NO. DL-5 6910496, JANUARY 1969

HIGH-FREQUENCY INTERMEDIATE-POWER TRANSISTORS

- 15 Watts at 100°C Case Temperature
- Typ $V_{CE(sat)}$ of 0.2 V at 200 mA
- Typ V_{BE} of 0.8 V at 200 mA
- Typ f_T of 50 MHz at 10 V, 100 mA

mechanical data



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absolute maximum ratings at 25°C case temperature (unless otherwise noted)

| | T1486 | T1487 |
|--|--------------------|--------------------|
| Collector-Base Voltage | ← 80 V → | ← 80 V → |
| Collector-Emitter Voltage (See Note 1) | ← 60 V → | ← 60 V → |
| Emitter-Base Voltage | ← 6 V → | ← 6 V → |
| Continuous Collector Current | ← 1 A → | ← 1 A → |
| Peak Collector Current (See Note 2) | ← 1.5 A → | ← 1.5 A → |
| Safe Operating Region at (or below) 100°C Case Temperature | See Figure 8 | |
| Continuous Device Dissipation at (or below) 100°C Case Temperature (See Note 3) | ← 15 W → | ← 15 W → |
| Continuous Device Dissipation at (or below) 25°C Free-Air Temperature (See Note 4) | 1 W | 2 W |
| Operating Case Temperature Range | ← -65°C to 200°C → | ← -65°C to 200°C → |
| Storage Temperature Range | ← -65°C to 200°C → | ← -65°C to 200°C → |

- NOTES: 1. These values apply when the base-emitter diode is open-circuited.
 2. This value applies for $t_p \leq 0.3$ ms, duty cycle $\leq 10\%$.
 3. Derate linearly to 200°C case temperature at the rate of 150 mW/deg.
 4. Derate linearly to 200°C free-air temperature at the rate of 5.7 mW/deg for the T1486 and 11.4 mW/deg for the T1487.

TYPES TI486, TI487

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

electrical characteristics at 25°C case temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------|--|---|-----|-----|-----|---------|
| $V_{(BR)CBO}$ | Collector-Base Breakdown Voltage | $I_C = 100 \mu A, I_E = 0$ | 80 | | | V |
| $V_{(BR)CEO}$ | Collector-Emitter Breakdown Voltage | $I_C = 30 \text{ mA}, I_B = 0$, See Note 5 | 60 | | | V |
| I_{CES} | Collector Cutoff Current | $V_{CE} = 60 \text{ V}, V_{BE} = 0$ | | | 3 | μA |
| | | $V_{CE} = 60 \text{ V}, V_{BE} = 0, T_C = 150^\circ C$ | | | 300 | |
| I_{EBO} | Emitter Cutoff Current | $V_{EB} = 6 \text{ V}, I_C = 0$ | | | 20 | μA |
| h_{FE} | Static Forward Current Transfer Ratio | $V_{CE} = 5 \text{ V}, I_C = 200 \text{ mA}$, See Notes 5 and 6 | 20 | | 80 | |
| V_{BE} | Base-Emitter Voltage | $I_B = 20 \text{ mA}, I_C = 200 \text{ mA}$, See Notes 5 and 6 | | 0.8 | 2 | V |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $I_B = 20 \text{ mA}, I_C = 200 \text{ mA}$, See Notes 5 and 6 | | 0.2 | 2 | V |
| h_{fe} | Small-Signal Common-Emitter Forward Current Transfer Ratio | $V_{CE} = 10 \text{ V}, I_C = 100 \text{ mA}, f = 10 \text{ MHz}$ | | 5 | | |
| C_{obo} | Common-Base Open-Circuit Output Capacitance | $V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 30 | | pF |

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NOTES: 5. These parameters must be measured using pulse techniques. $t_p = 300 \mu s$, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

thermal characteristics

| PARAMETER | | TI486 | TI487 | UNIT |
|----------------|---|-------|-------|-------|
| | | MAX | MAX | |
| θ_{J-C} | Junction-to-Case Thermal Resistance | 6.67 | 6.67 | deg/W |
| θ_{J-A} | Junction-to-Free-Air Thermal Resistance | 175 | 87.5 | |

TYPES T1486, T1487

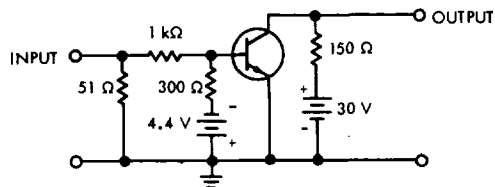
N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

switching characteristics at 25°C case temperature

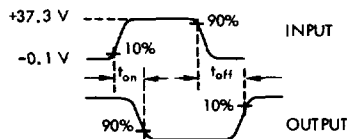
| PARAMETER | TEST CONDITIONS† | TYP | UNIT |
|-------------------------|---|------|---------------|
| t_{on} Turn-On Time | $I_C = 200 \text{ mA}$, $I_{B(1)} = 20 \text{ mA}$, $I_{B(2)} = -20 \text{ mA}$, | 0.14 | μs |
| t_{off} Turn-Off Time | $V_{BE(off)} = -3.4 \text{ V}$, $R_L = 150 \Omega$, See Figure 1 | 2.6 | |

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

FIGURE 1

- NOTES:
- The input waveform is supplied by a generator with the following characteristics: $t_r \leq 15 \text{ ns}$, $t_f \leq 15 \text{ ns}$, $Z_{out} = 50 \Omega$, $t_p = 10 \mu\text{s}$, duty cycle $\leq 2\%$.
 - Waveforms are monitored on an oscilloscope with the following characteristics: $t_r \leq 15 \text{ ns}$, $R_{in} \geq 10 \text{ M}\Omega$, $C_{in} \leq 11.5 \text{ pF}$.
 - Resistors must be noninductive types.
 - The d-c power supplies may require additional bypassing in order to minimize ringing.

TYPES TI486, TI487

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPICAL CHARACTERISTICS

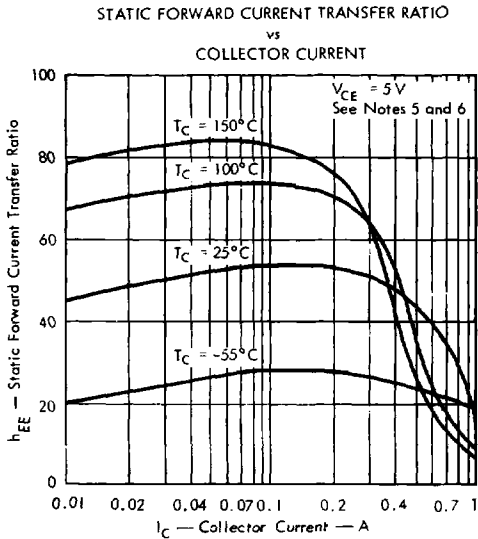


FIGURE 2

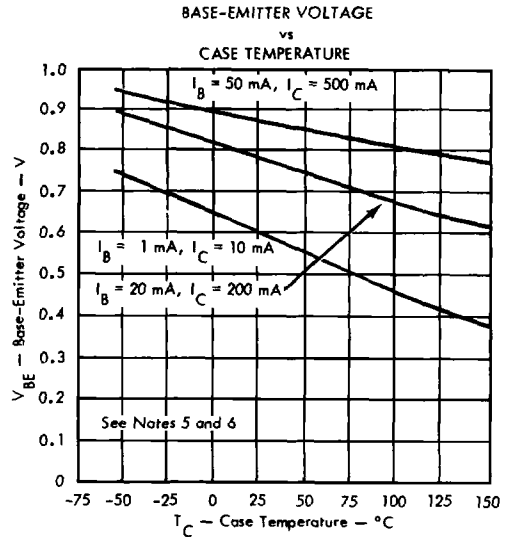


FIGURE 3

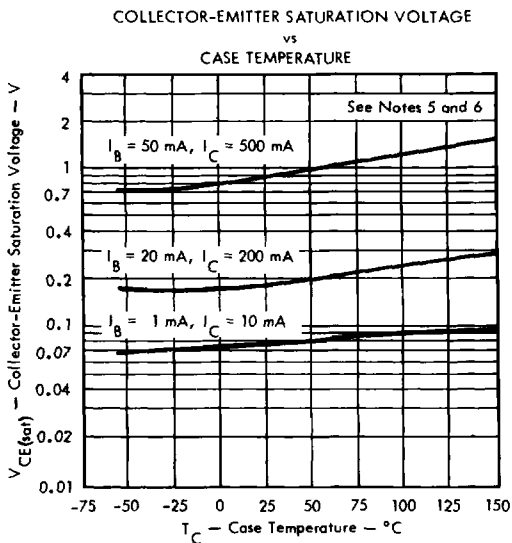


FIGURE 4

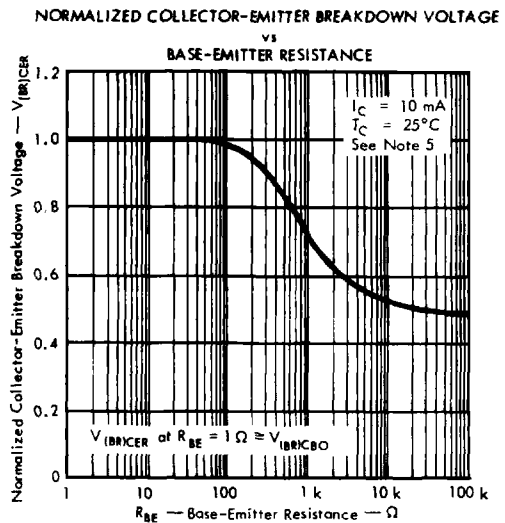


FIGURE 5

NOTES: 5. These parameters must be measured using pulse techniques. $t_p = 300\ \mu s$, duty cycle $\leq 2\%$.

6. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

TYPES T1486, T1487 N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

TYPICAL CHARACTERISTICS

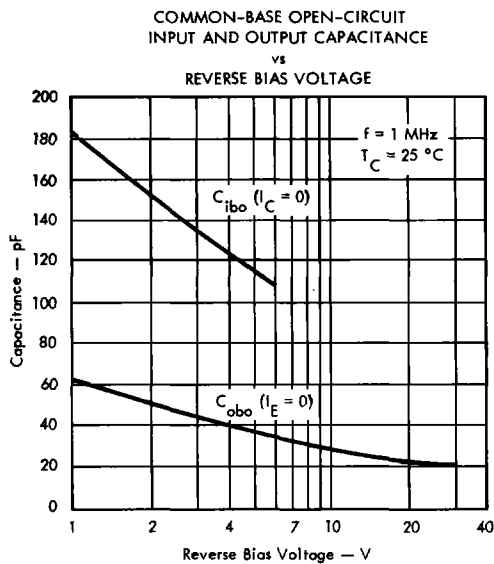


FIGURE 6

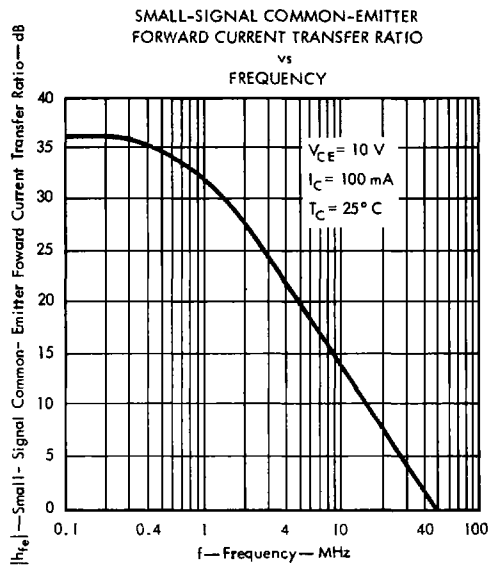


FIGURE 7

MAXIMUM SAFE OPERATING REGION

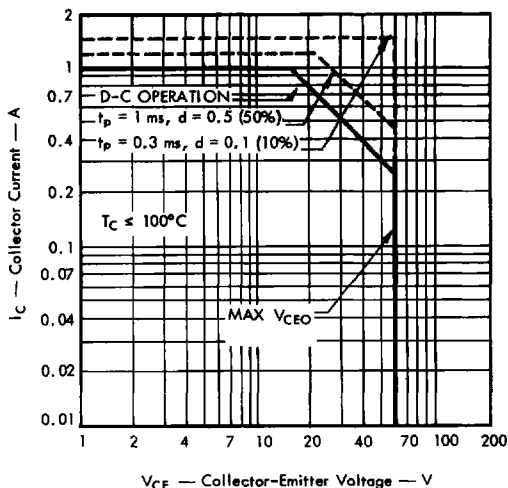


FIGURE 8

TYPES TI486, TI487

N-P-N TRIPLE-DIFFUSED PLANAR SILICON POWER TRANSISTORS

THERMAL INFORMATION

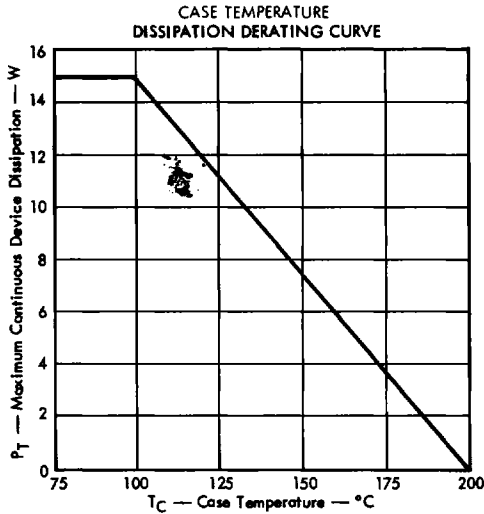


FIGURE 9

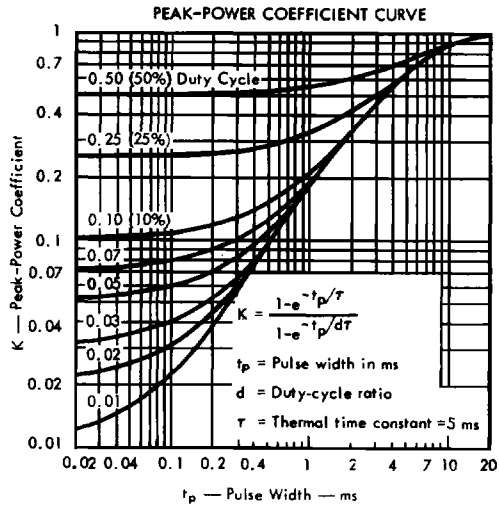


FIGURE 10

SYMBOL DEFINITION

| SYMBOL | DEFINITION | VALUE | | UNIT |
|-----------------|--|---------------|-------|-------|
| | | TI486 | TI487 | |
| $P_{T(av)}$ | Average Power Dissipation | | | W |
| $P_{T(max)}$ | Peak Power Dissipation | | | W |
| θ_{J-A} | Junction-to-Free-Air Thermal Resistance | 175 | 87.5 | deg/W |
| θ_{J-C} | Junction-to-Case Thermal Resistance | 6.67 | 6.67 | deg/W |
| θ_{C-A} | Case-to-Free-Air Thermal Resistance | 168 | 81 | deg/W |
| θ_{C-HS} | Case-to-Heat-Sink Thermal Resistance | | | deg/W |
| θ_{HS-A} | Heat-Sink-to-Free-Air Thermal Resistance | | | deg/W |
| T_A | Free-Air Temperature | | | °C |
| T_C | Case Temperature | | | °C |
| $T_{J(av)}$ | Average Junction Temperature | ≤ 200 | | °C |
| $T_{J(max)}$ | Peak Junction Temperature | ≤ 200 | | °C |
| K | Peak-Power Coefficient | See Figure 10 | | |
| t_p | Pulse Width | | | ms |
| t_x | Pulse Period | | | ms |
| d | Duty-Cycle Ratio (t_p/t_x) | | | |

Equation No. 1 — Application: d-c power dissipation, heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-C} + \theta_{C-HS} + \theta_{HS-A}} \text{ as in Figure 9 for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C}$$

Equation No. 2 — Application: d-c power dissipation, no heat sink used.

$$P_{T(av)} = \frac{T_{J(av)} - T_A}{\theta_{J-A}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Equation No. 3 — Application: Peak power dissipation, heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}} \text{ for } 100^\circ\text{C} \leq T_C \leq 200^\circ\text{C}$$

Equation No. 4 — Application: Peak power dissipation, no heat sink used.

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d\theta_{C-A} + K\theta_{J-C}} \text{ for } 25^\circ\text{C} \leq T_A \leq 200^\circ\text{C}$$

Solution:

From Figure 10, Peak-Power Coefficient

$K = 0.11$ and by use of equation No. 3

$$P_{T(max)} = \frac{T_{J(max)} - T_A}{d(\theta_{C-HS} + \theta_{HS-A}) + K\theta_{J-C}}$$

$$P_{T(max)} = \frac{200 - 50}{0.1(7) + 0.11(6.67)} = 105 \text{ W}$$

Example — Find $P_{T(max)}$ (design limit)

OPERATING CONDITIONS:

$$\theta_{C-HS} + \theta_{HS-A} = 7 \text{ deg/W (From information supplied with heat sink.)}$$

$$T_{J(av)} \text{ (design limit)} = 200^\circ\text{C}$$

$$T_A = 50^\circ\text{C}$$

$$d = 10\% (0.1)$$

$$t_p = 0.1 \text{ ms}$$